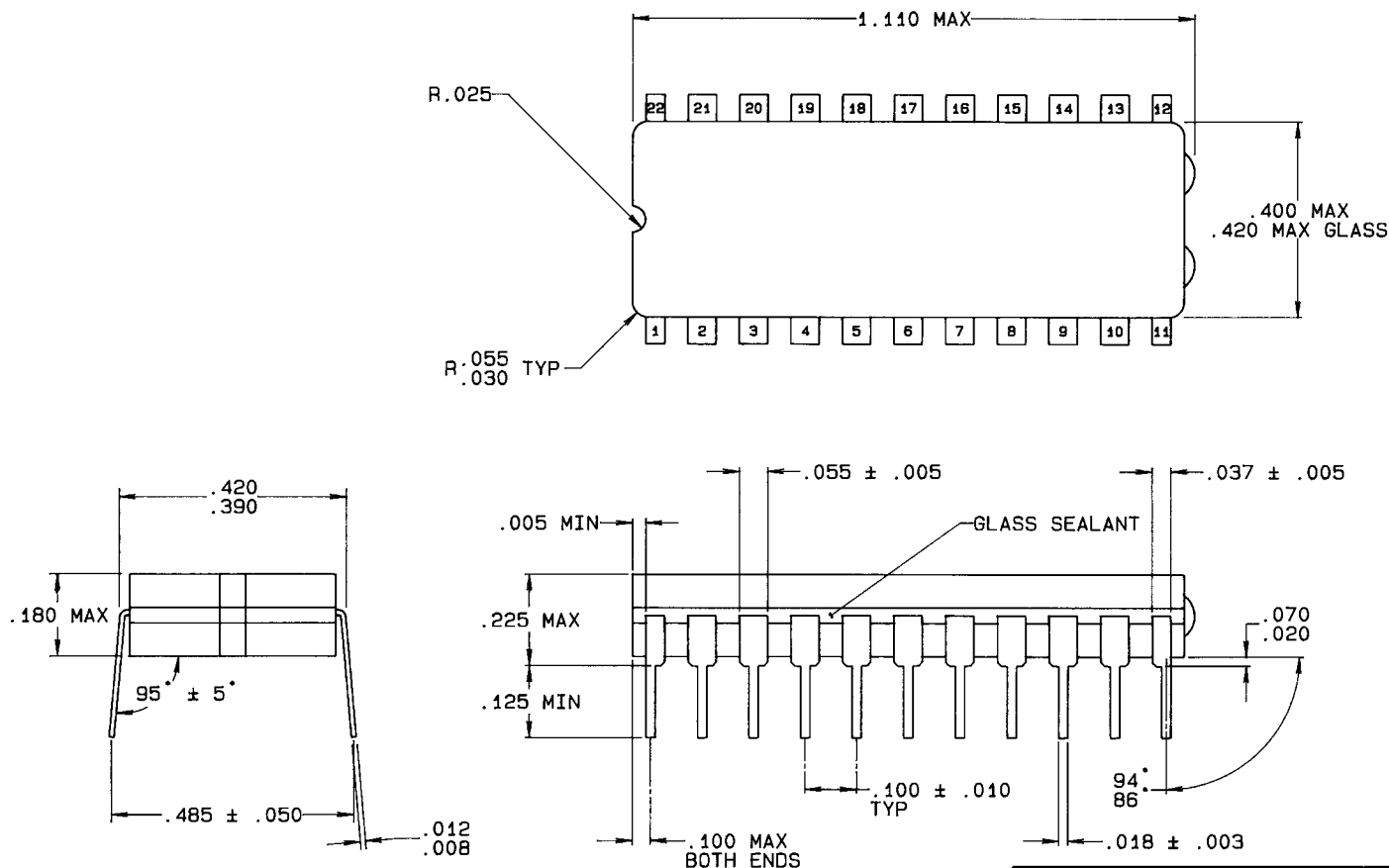


THIS DRAWING IS THE PROPERTY OF NATIONAL SEMICONDUCTOR CORPORATION. NO USE THEREOF SHALL BE MADE OTHER THAN AS A REFERENCE FOR PROPOSALS AS SUBMITTED TO NATIONAL SEMICONDUCTOR CORPORATION FOR JOBS TO BE EXECUTED IN CONFORMITY WITH SUCH PROPOSALS UNLESS THE CONSENT OF SAID NATIONAL SEMICONDUCTOR CORPORATION HAS PREVIOUSLY BEEN OBTAINED. NO PART OF THIS DRAWING SHALL BE COPIED OR DUPLICATED OR ITS CONTENTS DISCLOSED. THE INFORMATION CONTAINED ON THIS DRAWING IS CONFIDENTIAL AND PROPRIETARY.

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
G	ADD END LEAD DIM. .037±.005, CHANGE FULL LEAD DIM. FROM .060±.005 TO .055±.005, ADD .005, REVISED NOTES AND REDRAW.	02013	11/21/84	Y.T.H.



MIL/AERO
CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 200 TO 800 MICROINCHES TIN PLATE OVER 50 TO 300 MICROINCHES NICKEL UNDERPLATE OR BASIS METAL.
 - 50 TO 100 MICROINCHES GOLD OVER 50 TO 350 MICROINCHES NICKEL UNDERPLATE.

APPROVALS		DATE		NATIONAL SEMICONDUCTOR CORPORATION	
DRAWN Y.T.H.		11/21/84		2900 Semiconductor Drive, Santa Clara, Calif. 95051	
DFTG. CHK. J. CASTRO		11/27/84		CERDIP (J), 22 LEAD	
ENGR. CHK. J. CASTRO		12/5/84			
APPROVAL					
PROJECTION INCH MM		SCALE N/A	SIZE B	DRAWING NUMBER MKT-J22A	REV G
FORMERLY: N/A				SHEET 1 OF 1	